

REMARKS

Claim Rejections - 35 USC § 112

3. Claims 9-16 and 25-34 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The method step: "... simultaneously fusion bonding ..." (Claim 9, line 12; claim 26, line 15) is a subject matter which was not disclosed in the application as filed. The examiner is at a loss to determine the simultaneous step of fusion bonding or any simultaneous step claimed in the invention.

Response to Arguments

4. Applicant's arguments filed 7/01/04 have been fully considered but they are not persuasive for the following reasons:

Applicant recites inter alia: "...simultaneously fusion bonding ..." (Claim 9, line 12; claim 26, line 15). The Examiner's position as stated in the preceding Action was and continues to be that since the Applicant's amended step of "simultaneous fusion bonding" is not properly described in the specification and raise doubt as to the possession of the amended, claimed invention at the time of filing.

The Examiner's rejection is respectfully traversed.

Simultaneous fusion bonding is disclosed at, e.g., page 13 line 21 et seq. of the application. For example, at page 13 line 22 et seq. it is specifically disclosed that:

A stack of substrate layers, in which each substrate layer typically has one or two metal layers etched onto surfaces, are bonded to form a multilayer structure.

Furthermore, at page 15 line 22 et seq. the application discloses:

Fusion is accomplished in an autoclave or hydraulic press by first heating substrates past the PTFE melting point. Alignment of layers is secured by a fixture with pins to stabilize flow. During the process, the PTFE resin changes state to a viscous liquid, and adjacent layers fuse under pressure.

The foregoing examples make clear that what is being fused is "a stack of substrate layers." In addition, the disclosure of Section i. Final Assembly" at page 27 lines 6 et seq. further discloses that that multiple layers are being simultaneously bonded.

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To the extent that simultaneous fusion bonding is not fully described in the text of the application papers as filed, it is disclosed by its explicit incorporation into the present application. In particular, the present application, as filed, explicitly states:

The vertically-connected stripline structure described herein comprises a stack of substrate layers. A substrate "layer" is defined as a substrate including circuitry on one or both sides. A process for constructing such a multilayer structure is disclosed by U.S. Patent Application No. 09/199,675 entitled "Method of Making Microwave Multifunction Modules Using Fluoropolymer Composite Substrates, filed November 25, 1998, incorporated herein by reference. Not that references to "substrate layer" and "metal layer" herein are often referred to as "layer" and "metallization", respectively, in U.S. Patent Application No. 09/199,675.

The 09/199,675 application issued as U.S. Patent No. 6,099,677 on August 8, 2000 and discloses a method for simultaneous fusion bonding of Fluoropolymer layers. The Examiner is referred to, e.g., Col. 6, lines 31-60 and Col. 9 line 56 through Col. 17 line 31 of US 6,099,677 which describe simultaneous fusion bonding of fluoropolymer layers.

It is respectfully submitted that the Examiner's rejection under § 112 is overcome because a method for simultaneous fusion bonding was explicitly incorporated into the patent application as of the date of filing of this application.

A printed copy of US 6,099,677 is included for the Examiner's convenience.

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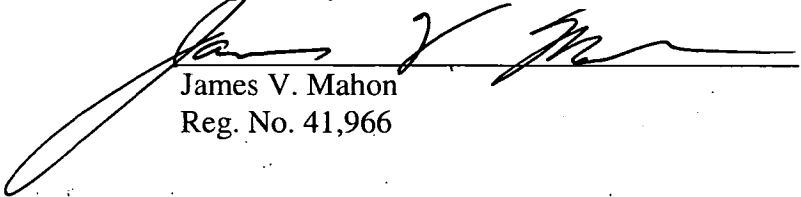
CONCLUSION

Claims 9-16 and 25-34 are now pending and believed to be in condition for allowance. Applicant respectfully requests that the Examiner withdraw his rejections and that the pending claims be allowed.

Please apply any credits or excess charges to our deposit account number 50-0521.

Date: January 20, 2005

Respectfully submitted,



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